

PROCESS CAPABILITIES		
Layer Count: Single – 1 to 42 layers		
Laminate Types: FR-4 (140Tg, 170Tg, 180Tg) (all UL94V-0 rated), RF and Teflon, Arlon, Getek, Rogers, Nelco and more! Thermal materials including Laird, Arlon, Ventec, Iteq and Chin-Shi, bonded to Aluminum or Copper.		
Laminate Thickness: 0.003” to 0.250”		
Copper Weight: 1/2 ounce to 20 ounce, finished		
Line & Space Widths: 0.003”/0.003”		
Specifications	Standard Technology	Advanced Technology
Number of Layers	1-12	14-42
Board Material	Ventec VT-47	Arlon Materials
	Isola FR408	Megtron 6
	Iteq IT-180	Mitsui
	DuPont Kapton	FR408
	Rogers - 4000 Series	Getek
	Epoxy Adhesive System	Nelco 4000 Series
	DuPont FR & LF	Rogers 3000 Series
	Acrylic Adhesive System	Rogers 5000 Series
	DuPont AP	Rogers 6000 Series
	Adhesiveless System	Hitachi Theta
		Taconic TLY
		Polyimide
		Mitsubishi BT
		Berquest
Minimum Board Thickness	2 layer - 0.010”	2 layer - 0.005”
	4 layer - 0.020”	4 layer - 0.010”
	6 layer - 0.040”	6 layer - 0.031”
	8 layer - 0.062”	8 layer - 0.040”
	10 layer - 0.062”	
	12 layer - 0.062”	
Maximum Board Thickness	2 layer - 0.125”	0.250” - 0.325”
	3-12 layer - 0.200”	
Maximum Board Size	16.5” x 22.5”	17.0” X 23.0”
Layer Count Rigid	18 Layers	36 Layers
Layer Count Flex	6 Layers	12 Layers
Layer Count Rigid Flex	10 Layers	18 Layers
Copper Thickness	0.5 oz. - 3 oz.	4 oz. - 7oz.
Hole Aspect Ratio	0.4173611111	0.6256944444
Minimum Hole Size	0.008”	0.005”
Mechanical Drill	0.008”	0.005”
Laser Drill	0.004”	0.003”
Minimum Trace/Space	0.004”/0.004”	0.002”/0.002”
Minimum Drill-to-Copper	0.010”	0.003”
Minimum Pitch	0.004”	0.002”

PCB CAPABILITIES MATRIX

Final Finish	HASL	ENEPIG
	Lead Free HASL	Wire Bondable Gold
	ENIG	Electroless Gold
	Hard Gold	Selective Gold
	Gold Fingers	Immersion Tin
	Immersion Silver	
	OSP	
Solder Mask	LPI:	LPI:
	Green	Yellow
	Black	White
	Red	Orange
	Blue	Purple
	Clear	Magenta
		Dry Film
Coverlay	FR Coverlay	
	LF Coverlay	
	Flexible Soldermask	
Silk Screen	White	Green
	Black	Red
	Yellow	Blue
PCB Fabrication	Scoring	Jump Scoring
	Route	Milling
		Laser Rout
Additional Features	Plated Slots	Plated Edges
	Non-plated Slots	Plated Milling
	Controlled Dielectric	Plated Counter Bores & Counter Sinks
	Covered Vias	Edge Castellations
	Counter Sinks	Controlled Impedance
	Counter Bores	Silver Filled Vias
	Dual Access Flex	Non-Conductive Filled Vias
	Book Binder Flex	Copper Filled Vias
		Plated Half Holes with clean edges
Quality	IPC 6012 Class 1 & 2	IPC 6012 Class 3
	IPC 6013 Class 1 & 2	IPC 6013 Class 3
		ITAR
		ISO 9001/2015
		100% Netlist Testing
		TDR Testing
		X-Ray Fluorescence
Special Technology		Blind & Buried Vias
		Laser Drilled Vias
		Stacked micro Vias
		Copper Filled Vias
		Metal Backed Boards
		Rigid-Flex Boards
		Flex Boards
		Chip Modules
MILITARY SPECIFICATION PCB	Group A & B Certification	MI-P-55110
		MI-P-31032